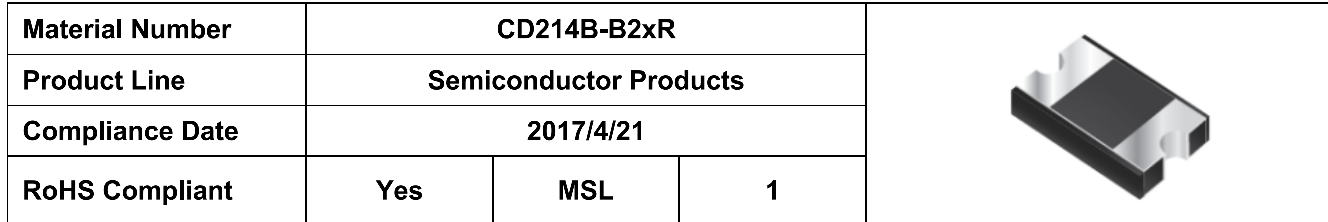
MATERIAL DECLARATION SHEET



Material Number	CD214B-B2xR		
Product Line	Semiconductor Products		
Compliance Date	2017/4/21		
RoHS Compliant	Yes	MSL	1

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	FRP	Others	24.36	Countinuous filament glass fibers	65997-17-3	43	24.940%	58.00%
				Copper foil	7440-50-8	14	8.120%	
				Filler	60676-86-0	10.21	5.920%	
				Curing Agent	9003-35-4	19.64	11.390%	
				Halogen Free Resin Blend	28064-14-4	13.15	7.630%	
2	Epoxy	Plastic	14.54	Silicon Dioxides	7631-86-9	57.14	19.87%	34.61%
				Bis-phenol type liquid epoxy	9003-36-5	42.86	14.74%	
3	Die Attach	Metal	0.89	Lead[*2]	7439-92-1	88	1.871%	2.13%
				Tin	7440-31-5	10	0.213%	
				Silver	7440-22-4	2	0.043%	
4	Dice	Others	1.37	Silicon	7440-21-3	97.98	3.196%	3.26%
				Titanium	7440-32-6	0.01	0.0003%	
				Nickel	7440-02-0	0.01	0.0003%	
				Silver	7440-22-4	2	0.065%	
5	Terminal Plating	Metal	0.84	Tin	7440-31-5	99.9	1.998%	2.00%
				Others	-	0.1	0.00200%	
		Total weight	42					

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This Document was updated on: 2024/12/20

Important remarks:

1. **It is the responsibility of the user to verify they are accessing the latest version.**
2. **Excepted for RoHS 7(a)-Lead in high melting temperature type solders (i.e. lead- based alloys containing 85% by weight or more lead).**

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